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## FSCM0565R

## Green Mode Fairchild Power Switch (FPS ${ }^{\text {TM }}$ )

## Features

- Internal Avalanche Rugged SenseFET
- Low Start-up Current (max 40uA)
- Low Power Consumption under 1 W at 240 VAC and 0.4W Load
- Precise Fixed Operating Frequency ( 66 kHz )
- Frequency Modulation for low EMI
- Pulse by Pulse Current Limiting (Adjustable)
- Over Voltage Protection (OVP)
- Over Load Protection (OLP)
- Thermal Shutdown Function (TSD)
- Auto-Restart Mode
- Under Voltage Lock Out (UVLO) with Hysteresis
- Built-in Soft Start (15ms)


## Application

- SMPS for VCR, SVR, STB, DVD and DVCD
- Adaptor
- SMPS for LCD Monitor


## Related Application Notes

- AN-4137: Design Guidelines for Off-line Flyback Converters Using Fairchild Power Switch (FPS)
- AN-4140: Transformer Design Consideration for off-line Flyback Converters using Fairchild Power Switch
- AN-4141: Troubleshooting and Design Tips for Fairchild Power Switch Flyback Applications
- AN-4148: Audible Noise Reduction Techniques for FPS Applications


## Description

The FSCM0565R is an integrated Pulse Width Modulator (PWM) and SenseFET specifically designed for high performance offline Switch Mode Power Supplies (SMPS) with minimal external components. This device is an integrated high voltage power switching regulator which combines an avalanche rugged SenseFET with a current mode PWM control block. The PWM controller includes integrated fixed frequency oscillator, under voltage lockout, leading edge blanking (LEB), optimized gate driver, internal soft start, temperature compensated precise current sources for a loop compensation, and self protection circuitry. Compared with a discrete MOSFET and PWM controller solution, it can reduce total cost, component count, size, and weight while simultaneously increasing efficiency, productivity, and system reliability. This device is a basic platform well suited for cost effective designs of flyback converters.

| OUTPUT POWER TABLE |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: |
| PRODUCT | $230 \mathrm{VAC} \pm 15 \%{ }^{(3)}$ |  | $85-265 \mathrm{VAC}$ |  |
|  | Adapt- <br> $\mathrm{er}^{(1)}$ | Open <br> Frame $^{(2)}$ | Adapt- <br> er $^{(1)}$ | Open <br> Frame $^{(2)}$ |
|  | 50 W | 65 W | 40 W | 50 W |
| FSCM0765RJ | 65 W | 70 W | 50 W | 60 W |
| FSCM0565RI | 50 W | 65 W | 40 W | 50 W |
| FSCM0765RI | 65 W | 70 W | 50 W | 60 W |
| FSCM0565RG | 70 W | 85 W | 60 W | 70 W |
| FSCM0765RG | 85 W | 95 W | 70 W | 85 W |

Table 1. Maximum Output Power

## Notes:

1. Typical continuous power in a non-ventilated enclosed adapter measured at $50^{\circ} \mathrm{C}$ ambient.
2. Maximum practical continuous power in an open-frame design at $50^{\circ} \mathrm{C}$ ambient.
3. 230 VAC or $100 / 115$ VAC with doubler.

## Typical Circuit



Figure 1. Typical Flyback Application

## Internal Block Diagram



Figure 2. Functional Block Diagram of FSCM0565R

## Pin Definitions

| Pin Number | Pin Name | Pin Function Description |
| :---: | :---: | :--- |
| 1 | Drain | This pin is the high voltage power SenseFET drain. It is designed to drive the <br> transformer directly. |
| 2 | GND | This pin is the control ground and the SenseFET source. |
| 3 | Vcc | This pin is the positive supply voltage input. Initially, During start up, the power is <br> supplied through the startup resistor from DC link. When Vcc reaches 12V, the <br> power is supplied from the auxiliary transformer winding. |
| 4 | Feedback (FB) | This pin is internally connected to the inverting input of the PWM comparator. <br> The collector of an optocoupler is typically tied to this pin. For stable operation, a <br> capacitor should be placed between this pin and GND. If the voltage of this pin <br> reaches 6.0V, the over load protection is activated resulting in shutdown of the <br> FPS. |
| 5 | N.C. | This pin is not connected. |
| 6 | limit | This pin is for the pulse by pulse current limit level programming. By using a <br> resistor to GND on this pin, the current limit level can be changed. If this pin is <br> left floating, the typical current limit will be 2.5A. |

## Pin Configuration



Figure 3. Pin Configuration (Top View)

## Absolute Maximum Ratings

( $\mathrm{Ta}=25^{\circ} \mathrm{C}$, unless otherwise specified.)

| Parameter | Symbol | Value | Unit |
| :---: | :---: | :---: | :---: |
| Drain-Source (GND) Voltage ${ }^{(1)}$ | VDSS | 650 | V |
| Drain-Gate Voltage (RGS=1MS) | VDGR | 650 | V |
| Gate-Source (GND) Voltage | VGS | $\pm 30$ | V |
| Drain Current Pulsed ${ }^{(2)}$ | IDM | 20 | ADC |
| Continuous Drain Current (D2-PAK, I2-PAK) |  |  |  |
| @ Tc = $25^{\circ} \mathrm{C}$ | ID | 3.9 | ADC |
| @ Tc = $100^{\circ} \mathrm{C}$ | ID | 2.5 | ADC |
| Continuous Drain Current (TO-220) |  |  |  |
| @ Tc = $25^{\circ} \mathrm{C}$ | ID | 5 | ADC |
| @ Tc = $100^{\circ} \mathrm{C}$ | ID | 3.2 | ADC |
| Supply Voltage | VCC | 20 | V |
| Analog Input Voltage Range | VFB | -0.3 to Vcc | V |
| Total Power Dissipation (D2-PAK,I2-PAK) | PD | 75 | W |
| Total Power Dissipation (TO-220) | PD | 120 | W |
| Operating Junction Temperature | TJ | Internally limited | ${ }^{\circ} \mathrm{C}$ |
| Operating Ambient Temperature | TA | -25 to +85 | ${ }^{\circ} \mathrm{C}$ |
| Storage Temperature Range | TSTG | -55 to +150 | ${ }^{\circ} \mathrm{C}$ |
| ESD Capability, HBM Model <br> (All pins except Vfb) | - | $\begin{gathered} 2.0 \\ (\mathrm{GND}-\mathrm{Vfb}=1.5 \mathrm{kV}) \\ (\mathrm{Vcc}-\mathrm{Vfb}=1.0 \mathrm{kV}) \end{gathered}$ | kV |
| ESD Capability, Machine Model (All pins except Vfb) | - | $\begin{gathered} 300 \\ (\text { GND-Vfb }=250 \mathrm{~V}) \\ (\mathrm{Vcc}-\mathrm{Vfb}=100 \mathrm{~V}) \end{gathered}$ | V |

## Notes:

1. $\mathrm{T}_{\mathrm{j}}=25^{\circ} \mathrm{C}$ to $150^{\circ} \mathrm{C}$
2. Repetitive rating: Pulse width limited by maximum junction temperature.

## Thermal Impedance

| Parameter | Symbol | Value | Unit |
| :--- | :---: | :---: | :---: |
| Junction-to-Ambient Thermal | $\theta \mathrm{JA}^{(1)}$ | - | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| Junction-to-Case Thermal (D2-PAK, I2-PAK) | $\theta \mathrm{JC}^{(2)}$ | 1.7 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| Junction-to-Case Thermal (TO-220) | $\theta \mathrm{JC}^{(2)}$ | 1.0 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |

## Note:

1. Free standing with no heat-sink under natural convection
2. Infinite cooling condition - Refer to the SEMI G30-88.

## Electrical Characteristics

( $\mathrm{Ta}=25^{\circ} \mathrm{C}$ unless otherwise specified.)

| Parameter | Symbol | Condition | Min. | Typ. | Max. | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| SenseFET SECTION |  |  |  |  |  |  |
| Drain Source Breakdown Voltage | BVDSS | VGS $=0 \mathrm{~V}, \mathrm{ID}=250 \mu \mathrm{~A}$ | 650 | - | - | V |
| Zero-Gate-Voltage Current | IDSS | $\begin{aligned} & \text { VDS }=\text { Max, Rating } \\ & \text { VGS }=0 \mathrm{~V} \end{aligned}$ | - | - | 500 | $\mu \mathrm{A}$ |
| Static Drain Source on Resistance ${ }^{(1)}$ | RDS(ON) | $V G S=10 \mathrm{~V}, \mathrm{ID}=2.3 \mathrm{~A}$ | - | 1.76 | 2.2 | $\Omega$ |
| Output Capacitance | Coss | $\begin{aligned} & \mathrm{VGS}=0 \mathrm{~V}, \mathrm{VDS}=25 \mathrm{~V}, \\ & \mathrm{f}=1 \mathrm{MHz} \end{aligned}$ | - | 78 | - | pF |
| Turn on Delay Time | TD(ON) | $\mathrm{V} D \mathrm{DD}=325 \mathrm{~V}, \mathrm{ID}=5 \mathrm{~A}$ | - | 22 | - |  |
| Rise Time | TR | time is essentially | - | 52 | - |  |
| Turn off Delay Time | TD(OFF) | independent of operating temperature) | - | 95 | - | ns |
| Fall Time | TF |  | - | 50 | - |  |
| CONTROL SECTION |  |  |  |  |  |  |
| Initial Frequency | Fosc | $\mathrm{VCC}=14 \mathrm{~V}, \mathrm{~V}_{\mathrm{FB}}=5 \mathrm{~V}$ | 60 | 66 | 72 | kHz |
| Modulated Frequency Range | $\Delta \mathrm{Fmod}$ | - | - | $\pm 3$ | - | kHz |
| Frequency Modulation Cycle | Tmod | - | - | 4 | - | ms |
| Voltage Stability | Fstable | $10 \mathrm{~V} \leq \mathrm{VCC} \leq 17 \mathrm{~V}$ | 0 | 1 | 3 | \% |
| Temperature Stability ${ }^{(2)}$ | $\triangle$ FOSC | $-25^{\circ} \mathrm{C} \leq \mathrm{Ta} \leq+85^{\circ} \mathrm{C}$ | - | $\pm 5$ | $\pm 10$ | \% |
| Maximum Duty Cycle | Dmax | - | 75 | 80 | 85 | \% |
| Minimum Duty Cycle | Dmin | - | - | - | 0 | \% |
| Start Threshold Voltage | Vstart | VFB $=$ GND | 11 | 12 | 13 | V |
| Stop Threshold Voltage | Vstop | VFB = GND | 7 | 8 | 9 | V |
| Feedback Source Current | IFB | VFB $=$ GND | 0.7 | 0.9 | 1.1 | mA |
| Soft-start Time | Tss | - | 10 | 15 | 20 | ms |
| BURST MODE SECTION |  |  |  |  |  |  |
| Burst Mode Voltages ${ }^{(2)}$ | VBH | $V C C=14 \mathrm{~V}$ | 0.4 | 0.5 | 0.6 | V |
|  | VBL | $\mathrm{VCC}=14 \mathrm{~V}$ | 0.24 | 0.3 | 0.36 | V |

## Notes:

1. Pulse Test: Pulse width $\leq 300 \mu \mathrm{~S}$, duty $\leq 2 \%$
2. These parameters, although guaranteed at the design, are not tested in mass production.

| PROTECTION SECTION |  |  |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Peak Current Limit ${ }^{(2)}$ | ILIM | $\mathrm{V}_{\mathrm{CC}}=14 \mathrm{~V}, \mathrm{~V}_{\mathrm{FB}}=5 \mathrm{~V}$ | 2.2 | 2.5 | 2.8 | A |
| Over Voltage Protection | Vovp | - | 18 | 19 | 20 | V |
| Thermal Shutdown Temperature ${ }^{(1)}$ | TsD |  | 130 | 145 | 160 | ${ }^{\circ} \mathrm{C}$ |
| ShutdownDelay Current | Idelay | $V_{F B}=4 \mathrm{~V}$ | 3.5 | 5.3 | 7 | $\mu \mathrm{A}$ |
| Shutdown Feedback Voltage | VSD | $\mathrm{V}_{\mathrm{FB}} \geq 5.5 \mathrm{~V}$ | 5.5 | 6 | 6.5 | V |
| TOTAL DEVICE SECTION |  |  |  |  |  |  |
| Startup Current | Istart |  | - | 20 | 40 | $\mu \mathrm{A}$ |
| Operating Supply Current ${ }^{(3)}$ | $\operatorname{lop}(\mathrm{MIN})$ | $\mathrm{VCC}=10 \mathrm{~V}, \mathrm{VFB}=0 \mathrm{~V}$ | - | 2.5 | 5 | mA |
|  | IOP(MAX) | $\mathrm{VCC}=20 \mathrm{~V}, \mathrm{VFB}=0 \mathrm{~V}$ |  |  |  |  |

## Notes:

1. These parameters, although guaranteed at the design, are not tested in mass production.
2. These parameters indicate the inductor current.
3. This parameter is the current flowing into the control IC.

## Comparison Between FSDM0565RB and FSCM0565R

| Function | FSDM0565RB | FSCM0565R |
| :--- | :--- | :--- |
| Frequency Modulation | $\mathrm{N} / \mathrm{A}$ | Available <br> • Modulated frequency range (DFmod) $= \pm 3 \mathrm{kHz}$ <br> - Frequency modulation cycle (Tmod) $=4 \mathrm{~ms}$ |
|  |  | - Programmable using external resistor (2.5A max) |
| Pulse-by-pulse Current Limit | • Internally fixed (2.25A) | - N/A (Requires a startup resistor) <br> - Startup current: 40uA (max) |
| Internal Startup Circuit | • Available |  |

## Typical Performance Characteristics

(These Characteristic Graphs are Normalized at $\mathrm{Ta}=25^{\circ} \mathrm{C}$.)


Figure 4. Startup Current vs. Temp


Figure 5 Stop Threshold Voltage vs. Temp


Figure 6. Maximum Duty Cycle vs. Temp


Figure 7. Start Threshold Voltage vs. Temp


Figure 8. Initial Freqency vs. Temp


Figure 9. Feedback Source Current vs. Temp

Typical Performance Characteristics (Continued)
(These Characteristic Graphs are Normalized at $\mathrm{Ta}=25^{\circ} \mathrm{C}$.)


Figure 10. Shutdown Feedback Voltage vs. Temp


Figure 11. Burst Mode Enable Voltage vs. Temp


Figure 12. Macimum Drain Current vs. Temp


Figure 13. Shutdown Delay Current vs. Temp


Figure 14. Burst Mode Disable Voltage vs. Temp


Figure 15. Operating Supply Current vs. Temp

## Functional Description

1. Startup: Figure 16 shows the typical startup circuit and transformer auxiliary winding for the FSCM0565R application. Before the FSCM0565R begins switching, it consumes only startup current (typically 25uA) and the current supplied from the DC link supply current consumed by the FPS (Icc), and charges the external capacitor ( $\mathrm{C}_{\mathrm{a}}$ ) that is connected to the Vcc pin. When Vcc reaches start voltage of 12 V (VSTART), the FSCM0565R begins switching, and the current consumed by the FSCM0565R increases to 3 mA . Then, the FSCM0565R continues its normal switching operation and the power required for this device is supplied from the transformer auxiliary winding, unless Vcc drops below the stop voltage of 8 V ( $\mathrm{V}_{\text {STOP }}$ ). To guarantee the stable operation of the control IC, Vcc has under voltage lockout (UVLO) with 4V hysteresis. Figure 17 shows the relation between the current consumed by the FPS (ICC) and the supply voltage ( $\mathrm{V}_{\mathrm{CC}}$ )


Figure 16. Startup Circuit


Figure 17. Relation Between Operating Supply Current and Vcc Voltage
The minimum current supplied through the startup resistor is given by

$$
I_{\text {sup }}{ }^{\min }=\left(\sqrt{2} \cdot V_{\text {line }}{ }^{m i n}-V_{\text {start }}\right) \cdot \frac{1}{R_{\text {str }}}
$$

where $V_{\text {line }}{ }^{\min }$ is the minimum input voltage, $V_{\text {start }}$ is the start voltage $(12 \mathrm{~V})$ and $R_{s t r}$ is the startup resistor. The startup resistor should be chosen so that $I_{s u p}{ }^{\text {min }}$ is larger than the maximum startup current ( 40 uA ). If not, $\mathrm{V}_{\mathrm{CC}}$ can not be charged to the start voltage and FPS will fail to start up.
2. Feedback Control: The FSCM0565R employs current mode control, as shown in Figure 18. An opto-coupler (such as the H11A817A) and a shunt regulator (such as the KA431) are typically used to implement the feedback network. Comparing the feedback voltage with the voltage across the Rsense resistor makes it possible to control the switching duty cycle. When the reference pin voltage of the KA431 exceeds the internal reference voltage of 2.5 V , the H11A817A LED current increases, thus pulling down the feedback voltage and reducing the duty cycle. This event typically happens when the input voltage is increased or the output load is decreased.
2.1 Pulse-by-pulse Current Limit: Because current mode control is employed, the peak current through the SenseFET is determined by the inverting input of the PWM comparator (Vfb*) as shown in Figure 18. When the current through the opto transistor is zero and the current limit pin (\#5) is left floating, the feedback current source (IFB) of 0.9 mA flows only through the internal resistor ( $\mathrm{R}+2.5 \mathrm{R}=2.8 \mathrm{k}$ ). In this case, the cathode voltage of diode D2 and the peak drain current have maximum values of 2.5 V and 2.5 A , respectively. The pulse-by-pulse current limit can be adjusted using a resistor to GND on the current limit pin (\#5). The current limit level using an external resistor (RLIM) is given by

$$
I_{L I M}=\frac{R_{L I M} \cdot 2.5 A}{2.8 k \Omega+R_{L I M}}
$$



Figure 18. Pulse Width Modulation (PWM) Circuit
2.2 Leading Edge Blanking (LEB): At the instant the internal SenseFET is turned on, there usually exists a high
current spike through the SenseFET, caused by primary-side capacitance and secondary-side rectifier reverse recovery. Excessive voltage across the Rsense resistor can lead to incorrect feedback operation in the current mode PWM control. To counter this effect, the FSCM0565R employs a leading edge blanking (LEB) circuit. This circuit inhibits the PWM comparator for a short time (TLEB) after the SenseFET is turned on.
3. Protection Circuit: The FSCM0565R has several self protective functions such as over load protection (OLP), over voltage protection (OVP) and thermal shutdown (TSD). Because these protection circuits are fully integrated into the IC without external components, the reliability can be improved without increasing cost. Once the fault condition occurs, switching is terminated and the SenseFET remains off. This causes Vcc to fall. When Vcc reaches the UVLO stop voltage of 8 V , the current consumed by the FSCM0565R decreases to the startup current (typically 25 uA ) and the current supplied from the DC link charges the external capacitor $\left(\mathrm{C}_{\mathrm{a}}\right)$ that is connected to the Vcc pin. When Vcc reaches the start voltage of 12 V , the FSCM0565R resumes its normal operation. In this manner, the auto-restart can alternately enable and disable the switching of the power SenseFET until the fault condition is eliminated (see Figure 19).


Figure 19. Auto Restart Operation
3.1 Over Load Protection (OLP): Overload is defined as the load current exceeding a pre-set level due to an unexpected event. In this situation, the protection circuit should be activated to protect the SMPS. However, even when the SMPS is in the normal operation, the over load protection circuit can be activated during the load transition. To avoid this undesired operation, the over load protection circuit is designed to be activated after a specified time to
determine whether it is a transient situation or an overload situation. Because of the pulse-by-pulse current limit capability, the maximum peak current through the SenseFET is limited, and therefore the maximum input power is restricted with a given input voltage. If the output consumes beyond this maximum power, the output voltage (Vo) decreases below the set voltage. This reduces the current through the opto-coupler LED, which also reduces the optocoupler transistor current, thus increasing the feedback voltage (Vfb). If Vfb exceeds 2.5 V , D1 is blocked and the 5.3 uA current source ( $\mathrm{I}_{\text {delay }}$ ) starts to charge $\mathrm{C}_{\mathrm{B}}$ slowly up to Vcc. In this condition, Vfb continues increasing until it reaches 6 V , when the switching operation is terminated as shown in Figure 20. The delay time for shutdown is the time required to charge CB from 2.5 V to 6.0 V with 5.3 uA (Idelay). In general, a $10 \sim 50 \mathrm{~ms}$ delay time is typical for most applications.


Figure 20. Over Load Protection
3.2 Over Voltage Protection (OVP): If the secondary side feedback circuit were to malfunction or a solder defect caused an open in the feedback path, the current through the opto-coupler transistor becomes almost zero. Then, Vfb climbs up in a similar manner to the over load situation, forcing the preset maximum current to be supplied to the SMPS until the over load protection is activated. Because more energy than required is provided to the output, the output voltage may exceed the rated voltage before the over load protection is activated, resulting in the breakdown of the devices in the secondary side. To prevent this situation, an over voltage protection (OVP) circuit is employed. In general, Vcc is proportional to the output voltage and the FSCM0565R uses Vcc instead of directly monitoring the output voltage. If VCC exceeds 19 V , an OVP circuit is activated resulting in the termination of the switching operation. To avoid undesired activation of OVP during normal operation, Vcc should be designed to be below 19V.
3.3 Thermal Shutdown (TSD): The SenseFET and the
control IC are built in one package. This makes it easy for the control IC to detect the heat generation from the SenseFET. When the temperature exceeds approximately $145^{\circ} \mathrm{C}$, the thermal protection is triggered resulting in shutdown of the FPS.
4. Frequency Modulation: EMI reduction can be accomplished by modulating the switching frequency of a switched power supply. Frequency modulation can reduce EMI by spreading the energy over a wider frequency range than the band width measured by the EMI test equipment. The amount of EMI reduction is directly related to the depth of the reference frequency. As can be seen in Figure 21, the frequency changes from 63 KHz to 69 KHz in 4 ms .


Figure 21. Frequency Modulation
5. Soft Start: The FSCM0565R has an internal soft start circuit that increases PWM comparator inverting input voltage together with the SenseFET current slowly after it starts up. The typical soft start time is 15 ms . The pulse width to the power switching device is progressively increased to establish the correct working conditions for transformers, rectifier diodes and capacitors. The voltage on the output capacitors is progressively increased with the intention of smoothly establishing the required output voltage. Preventing transformer saturation and reducing stress on the secondary diode during start up is also helpful.
6. Burst Operation: To minimize power dissipation in standby mode, the FSCM0565R enters into burst mode operation at light load condition. As the load decreases, the feedback voltage decreases. As shown in Figure 22, the device automatically enters into burst mode when the feedback voltage drops below VBL $(300 \mathrm{mV})$. At this point switching stops and the output voltages start to drop at a rate dependent on standby current load. This causes the feedback
voltage to rise. Once it passes VBH ( 500 mV ), switching resumes. The feedback voltage then falls, and the process repeats. Burst mode operation alternately enables and disables switching of the power SenseFET, thereby reducing switching loss in standby mode.


Figure 22. Waveforms of Burst Operation

## Typical application circuit

| Application | Output Power | Input Voltage | Output Voltage (Max Current) |
| :---: | :---: | :---: | :---: |
| LCD Monitor | 40 W | Universal Input | $5 \mathrm{~V}(2.0 \mathrm{~A})$ |
|  |  | $(85-265 \mathrm{Vac})$ | $12 \mathrm{~V}(2.5 \mathrm{~A})$ |

## Features

- High efficiency (>81\% at 85 Vac input)
- Low standby mode power consumption (<1W at 240 Vac input and 0.4 W load)
- Low component count
- Enhanced system reliability through various protection functions
- Low EMI through frequency modulation
- Internal soft-start (15ms)


## Key Design Notes

- Resistors R102 and R105 are employed to prevent start-up at low input voltage
- The delay time for over load protection is designed to be about 50 ms with C 106 of 47 nF . If a faster triggering of OLP is required, C 106 can be reduced to 22 nF .


## 1. Schematic



Figure 23. Demo Circuit
2. Transformer


Figure 24. Transformer Schematic Diagram

## 3.Winding Specification

| No | Pin (s $\rightarrow \mathbf{f})$ | Wire | Turns | Winding Method |
| :---: | :---: | :---: | :---: | :---: |
| Na | $4 \rightarrow 5$ | $0.2^{\phi} \times 1$ | 8 | Center Winding |
| Insulation: Polyester Tape $\mathrm{t}=0.050 \mathrm{~mm}, 2$ Layers |  |  |  |  |
| $\mathrm{Np} / 2$ | $2 \rightarrow 1$ | $0.4^{\phi} \times 1$ | 18 | Solenoid Winding |
| Insulation: Polyester Tape $\mathrm{t}=0.050 \mathrm{~mm}, 2$ Layers |  |  |  |  |
| N 12 V | $10 \rightarrow 8$ | $0.3^{\phi} \times 3$ | 7 | Center Winding |
| Insulation: Polyester Tape $\mathrm{t}=0.050 \mathrm{~mm}, 2 \mathrm{Layers}$ |  |  |  |  |
| N5V | $7 \rightarrow 6$ | $0.3^{\phi} \times 3$ | 3 | Center Winding |
| Insulation: Polyester Tape $\mathrm{t}=0.050 \mathrm{~mm}, 2$ Layers |  |  |  |  |
| Np/2 | $3 \rightarrow 2$ | $0.4^{\phi} \times 1$ | 18 | Solenoid Winding |
| Outer Insulation: Polyester Tape $\mathrm{t}=0.050 \mathrm{~mm}, 2 \mathrm{Layers}$ |  |  |  |  |

## 4.Electrical Characteristics

|  | Pin | Specification | Remarks |
| :--- | :---: | :---: | :---: |
| Inductance | $1-3$ | $520 \mathrm{uH} \pm 10 \%$ | $100 \mathrm{kHz}, 1 \mathrm{~V}$ |
| Leakage Inductance | $1-3$ | 10 uH Max | $2^{\text {nd }}$ all Short |

## 5. Core \& Bobbin

Core: EER 3016
Bobbin: EER3016
Ae(mm2): 96
6. Demo Circuit Part List

| Part | Value | Note | Part | Value | Note |
| :---: | :---: | :---: | :---: | :---: | :---: |
| Fuse |  |  | C301 | 4.7nF | Polyester Film Cap. |
| F101 | 2A/250V |  |  |  |  |
| NTC |  |  | Inductor |  |  |
| RT101 | 5D-9 |  | L201 | 5uH | Wire 1.2 mm |
| Resistor |  |  | L202 | 5 uH | Wire 1.2mm |
| R101 | 560K | 1W |  |  |  |
| R102 | 500K | 1/4W |  |  |  |
| R103 | 56K | 2W |  |  |  |
| R104 | 5 | 1/4W | Diode |  |  |
| R105 | 500K | 1/4W | D101 | UF4007 |  |
| R106 | 5K | 1/4W | D102 | TVR10G |  |
| R201 | 1K | 1/4W | D201 | MBRF1045 |  |
| R202 | 10K | 1/4W | D202 | MBRF10100 |  |
| R203 | 1.2K | 1/4W |  |  |  |
| R204 | 5.6K | 1/4W |  |  |  |
| R205 | 5.6K | 1/4W | Bridge Diode |  |  |
|  |  |  | BD101 | 2KBP06M 3N257 | Bridge Diode |
| Capacitor |  |  |  |  |  |
| C101 | 220nF/275VAC | Box Capacitor | Line Filter |  |  |
| C102 | 220nF/275VAC | Box Capacitor | LF101 | 23mH | Wire 0.4 mm |
| C103 | 100uF/400V | Electrolytic Capacitor | IC |  |  |
| C104 | 10nF/1kV | Ceramic Capacitor | IC101 | FSCM0565R | FPS ${ }^{\text {TM }}$ |
| C105 | 22uF/50V | Electrolytic Capacitor | IC201 | KA431(TL431) | Voltage Reference |
| C106 | 47nF/50V | Ceramic Capacitor | IC301 | H11A817A | Opto-coupler |
| C201 | 1000uF/25V | Electrolytic Capacitor |  |  |  |
| C202 | 1000uF/25V | Electrolytic Capacitor |  |  |  |
| C203 | 1000uF/10V | Electrolytic Capacitor |  |  |  |
| C204 | 1000uF/10V | Electrolytic Capacitor |  |  |  |
| C205 | 47nF/50V | Ceramic Capacitor |  |  |  |

## Package Dimensions

## D2-PAK-6L



NOTES: UNLESS OTHERWISE SPECIFIED
A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
D) DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994

## Package Dimensions (Continued)

## I2-PAK-6L (Forming)



NOTES: UNLESS OTHERWISE SPECIFIED
A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD.
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

## TO-220-6L (Forming)



## Ordering Information

| Product Number | Package | Marking Code | BVdss | Rds(on) Max. |
| :--- | :---: | :---: | :---: | :---: |
| FSCM0565RJ | D2-PAK-6L | CM0565R | 650 V | $2.2 \Omega$ |
| FSCM0565RIWDTU | I2-PAK-6L |  |  |  |
| FSCM0565RGWDTU | TO-220-6L |  |  |  |

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.
